IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of	:	
Yuuichiro KAJIWARA et al.	:	**Attn: APPLICATION BRANCH**
Serial No. NEW	:	**Docket No. 2001_1763A**
Filed November 28, 2001	:	

A LATEX FOR DIP MOLDING AND A DIP MOLDED PRODUCT

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to calculating the filing fee, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend the claims as follows:

4. **(Amended)** The latex for dip molding according to claim 1, wherein the emulsion polymerization is conducted by the use of redox type of polymerization initiator containing no transition metal salt.

8. **(Amended)** The latex for dip molding according to claim 1, wherein 100 parts by weight of the monomer mixture comprises 15 to 45 parts by weight of a vinyl cyanide monomer, 35 to 80 parts by weight of a conjugated diene monomer, 0.1 to 20 parts by weight of an ethylenically unsaturated carboxylic acid, and 0 to 20 parts by weight of other ethylenically unsaturated monomer copolymerizable with the above monomers.

9. **(Amended)** The latex for dip molding according to claim 1, wherein the emulsion polymerization of the monomer mixture is carried out in the presence of a seed polymer having an average particle diameter of 10 to 90 nm and a glass transition temperature (Tg) of -50 to 50°C obtained by emulsion polymerization of a vinyl cyanide monomer and an ethylenically unsaturated monomer copolymerizable therewith.

10. **(Amended)** A dip molded product produced by dip molding from the latex for dip molding described in claim 1.

REMARKS

The claims are amended to remove the multiple dependencies, so as to remove the improper multiple dependencies and to reduce the PTO filing fee.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached pages are captioned "**Version with markings to show changes made**".

Favorable action on the merits is solicited.

Respectfully submitted,

Yuuichiro KAJIWARA et al.

By [signature]
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Claims

Claim 1

A latex for dip molding, which is obtainable by emulsion polymerization of 100 parts by weight of a monomer mixture in the presence of 0.5 to 10.0 parts by weight of alkyl benzene sulfonate containing at least 10 weight % of C_{13-20} alkyl benzene sulfonate.

Claim 2

The latex for dip molding according to claim 1, wherein the alkyl benzene sulfonate contains at least 25 weight % of C_{13-20} alkyl benzene sulfonate.

Claim 3

The latex for dip molding according to claim 1, wherein the alkyl benzene sulfonate contains at least 40 weight % of C_{13-20} alkyl benzene sulfonate.

Claim 4 (Amended)

The latex for dip molding according to ~~any one of~~ claims 1 ~~to 3~~, wherein the emulsion polymerization is conducted by the use of redox type of polymerization initiator containing no transition metal salt.

Claim 5

The latex for dip molding according to claim 4, wherein the redox type polymerization initiator containing no transition metal salt is a combination product of an oil-soluble peroxide with a reducing agent.

Claim 6

The latex for dip molding according to claim 5, wherein the reducing agent is an alkali metal sulfonate or ammonium sulfonate.

Claim 7

The latex for dip molding according to claim 6, wherein the alkali metal sulfonate is sodium formaldehyde sulfoxylate.

Claim8 (Amended)

The latex for dip molding according to ~~any one of~~ claim~~s~~ 1 ~~to 7~~, wherein 100 parts by weight of the monomer mixture comprises 15 to 45 parts by weight of a vinyl cyanide monomer, 35 to 80 parts by weight of a conjugated diene monomer, 0.1 to 20 parts by weight of an ethylenically unsaturated carboxylic acid, and 0 to 20 parts by weight of other ethylenically unsaturated monomer copolymerizable with the above monomers.

Claim 9 (Amended)

The latex for dip molding according to ~~any one of~~ claim~~s~~ 1 ~~to 8~~, wherein the emulsion polymerization of the monomer mixture is carried out in the presence of a seed polymer having an average particle diameter of 10 to 90 nm and a glass transition temperature (Tg) of –50 to 50 °C obtained by emulsion polymerization of a vinyl cyanide monomer and an ethylenically unsaturated monomer copolymerizable therewith.

Claim 10 (Amended)

A dip molded product produced by dip molding from the latex for dip molding described in ~~any one of~~ claim~~s~~ 1 ~~to 9~~.

Claim 11

The dip molded product according to claim10, which is a glove or a fingerstalls.